

 $\begin{array}{cccc} R & & \vdots & & A0 \\ C & & N \ . \vdots & & \end{array}$

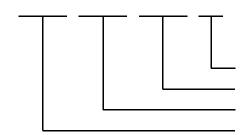
	Revision Record				
Control No.	Revision	Description	Date	Drawn	Approved

TMAX-1770-XXX-M M lded P e I d c

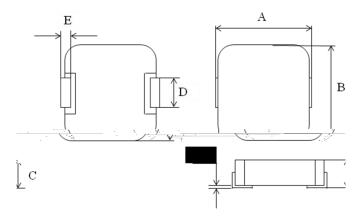
Features

Applications

Product Description



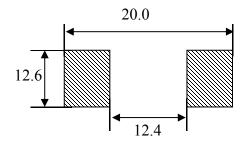
Dimensions



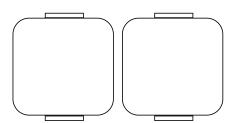
17.5 Max.	
17.15 Max.	
7.0 Max.	
11.8±0.3	
2.5±0.5	
0~0.30	

R C A0 N .:

Recommend Land Pattern Dimensions



Marking



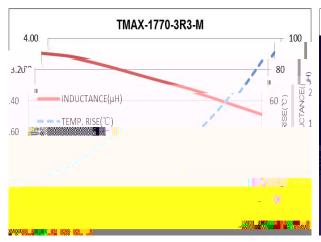
I a : 0.1 H

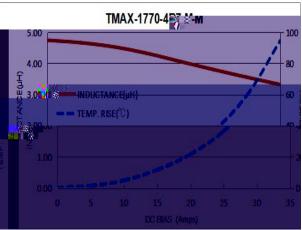
R : A0 C N ::

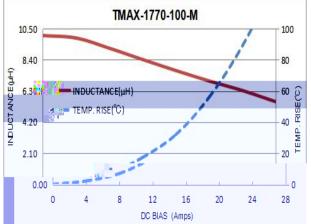
Notes:

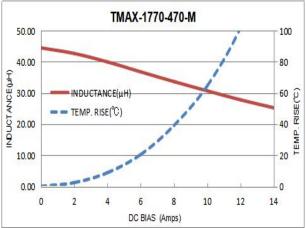
: (),

Inductance and Temperature Rise vs. DC Current



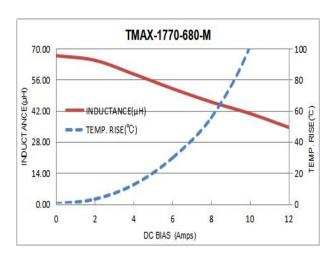








R C A0 N .:



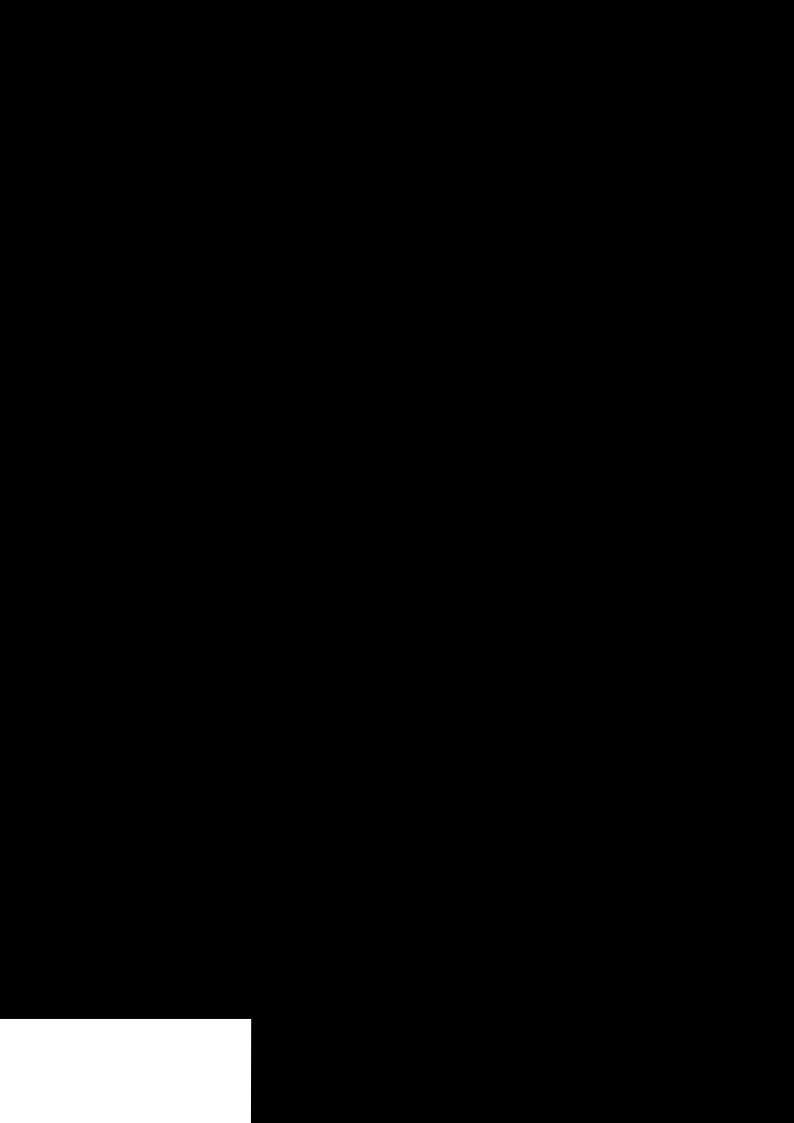
Reliability:

Item	Test Method	Specification and Requirement
	± ± °C ±	
		±



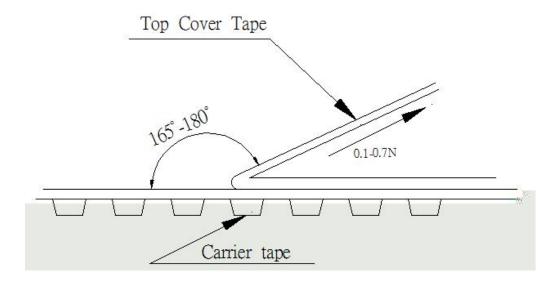
Reliability:

Item	Test Method	Specification and Requirement
	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	
	±	±
	±	
	±	
	±	



R C A0N .:

Peeling of top cover tape





R A0 C $N \mathrel{\dot{.}\dot{.}}$

Reflow Profile

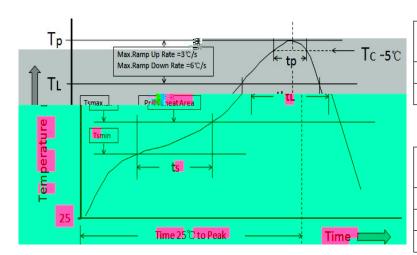


Table1-StandardSnPb Solder(Tc)

Package Thickness	Volume mm³ <350	Volume mm³ ≧350
<	$^{\circ}$	$^{\circ}$
<u></u>	$^{\circ}$	$^{\circ}$

Table2-Lead(Pb)Free Solder(Tc)

Package Thickness	Volume mm³ <350	Volume mm³ 350-2000	Volume mm³ >2000
<	°C	$^{\circ}$	$^{\circ}$
	°C	℃	J
	$^{\circ}$	$^{\circ}$	°C

Reference JDEC J-STD-020(latest revision)

Profile Feature	Standard SnPb solder	Lead(Pb) Free Solder
	$^{\circ}\mathbb{C}$	$^{\circ}\mathbb{C}$
	${\mathbb C}$	°C
	°C	$^{\circ}\mathbb{C}$
	${\mathbb C}$	$^{\circ}$ C
$^{\circ}\!\mathrm{C}$		
	°C	°C
${\mathbb C}$		



R A0 C N .:

Numbers of ping

Label marking

Production Label

Shipping Label

Care note for use

- > Storage Condition
- > Use Temperature



R : A0 C N .:

Care note for Safety